



All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 mm and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of the zQSFP+ Thru Bezel Cage Assembly, Heat Sink, EMI/Dust Cover, and Light Pipe that are used in conjunction with 38-position, 0.8 mm pitch, right-angle surface mount, zQSFP+ connectors used in the communications industry. The cage assembly serves as a housing for the connector and mating transceiver. The cage assembly is a frame with compliant pins for mounting onto the host printed circuit (pc) board. The cage assembly features front perimeter electromagnetic interference (EMI) springs. These springs block any EMI emissions emanating from the transceiver when installed. The cage assembly is designed to pass through the bezel. The cage assembly transceiver locking latches hold the transceiver in place, and the hard stop controls the insertion depth of the transceiver.

The EMI/dust cover is used to confine EMI emissions and prevent contaminants from entering the chassis when the transceiver is not installed.

In applications where heat dissipation is necessary, a heat sink can be used. The heat sink must be chosen to meet the need of the specific application. A sample of available heat sinks are shown in Figure 1. These heat sinks are designed to be attached to the cage assembly using a clip. This type allows insertion and extraction of the transceiver while maintaining the necessary contact between the heat sink and the transceiver. Basic terms and features of this product are provided in Figure 1.

The cage assemblies are available with or without a light pipe. The light pipe is used to transmit light from an LED on the pc board to a panel.

When corresponding with TE Connectivity (TE) personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

zQSFP+ Cage Assembly with Heat Sink and Clip

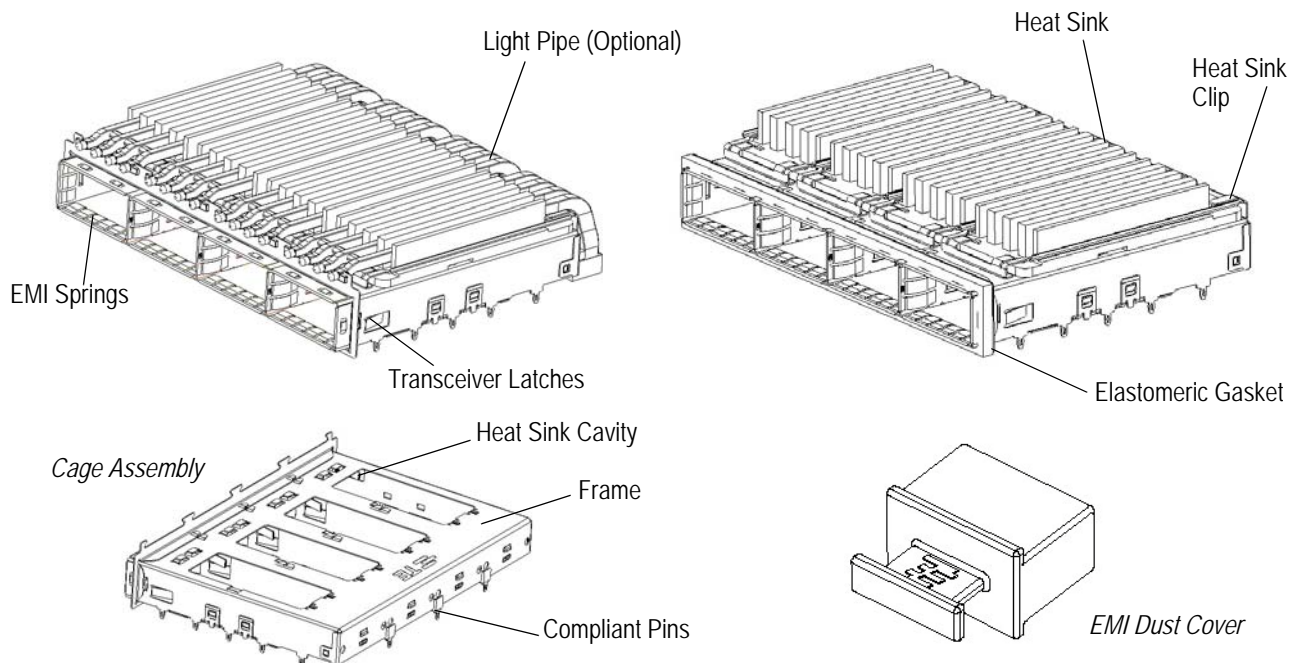


Figure 1

2. REFERENCE MATERIAL

2.1. Revision Summary

- Changed specification document in Paragraph 2.4

2.2. Customer Assistance

Reference Product Base Part Number 2227359 and Product Code L818 are representative of the zQSFP+ Thru Bezel Cage Assembly, Heat Sink, EMI/Dust Cover, and Light Pipe. Use of these numbers will identify the product line and help you to obtain product and tooling information. Such information can be obtained through a local TE representative, by visiting our website at www.te.com, or by calling PRODUCT INFORMATION or the TOOLING ASSISTANCE CENTER at the numbers at the bottom of page 1.

2.3. Drawings

Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the information contained in the Customer Drawings takes priority.

2.4. Specifications

Product Specification 108-19428 provides product performance and test information.

3. REQUIREMENTS

3.1. Safety

Do not stack component packages so high that the shipping containers buckle or deform.

3.2. Limitations

A. Transceiver Module

The top surface of the Transceiver Module is to be free of EMI bumps and maintain a flatness of 0.08 mm. The width of the mating transceiver module (outside of the cage assembly) cannot exceed 19 mm in order to prevent interference between transceivers inserted into adjacent ports.

B. Bezel

The bezel requirements given in this document are specifically configured for products used in the communications industry.



It is strongly recommended that this bezel configuration NOT be used for peripheral component interconnect (PCI) applications.

3.3. Material

The cage assembly frame is made of nickel silver alloy, and the EMI springs are made from copper alloy, tin-plated. The EMI/dust cover is made of zinc plated with tin over nickel. The heat sinks are made of aluminum. The heat sink clip is made of stainless steel. The light pipes are made of clear polycarbonate.

3.4. Storage

The cage assemblies should remain in the shipping containers until ready for use to prevent deformation to the contacts and compliant pins. The connectors should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

3.5. Chemical Exposure

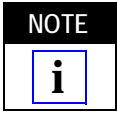
Do not store cage assemblies or accessories near any chemical listed below as they may cause stress corrosion cracking in the contacts or compliant pins.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur	Nitrites	Tartrates

3.6. Host PC Board

A. Material and Thickness

The host pc board material shall be glass epoxy (FR-4 or G-10). The pc board thickness shall be a minimum of 1.45 mm for mounting the cage assembly to one side of the pc board, and the pc board thickness must be 2.36 mm minimum when mounting the cage assembly to both sides of the pc board.



NOTE Contact *PRODUCT INFORMATION* at the number listed at the bottom of page 1 for suitability of other pc board materials.

B. Tolerance

Maximum allowable bow of the pc board shall be 0.08 mm over the length of the cage assembly. The coplanarity of the pc board circuit pads must be 0.03 mm.

C. Circuit Pads

The circuit pads must be solderable in accordance with EIA-364-52.

D. PC Board Layout

All holes and circuit pads must be precisely located on the pc board to ensure proper placement and optimum performance of the connector and cage assembly. Recommended circuit pad pattern, dimensions, and tolerances are provided in Figure 2.

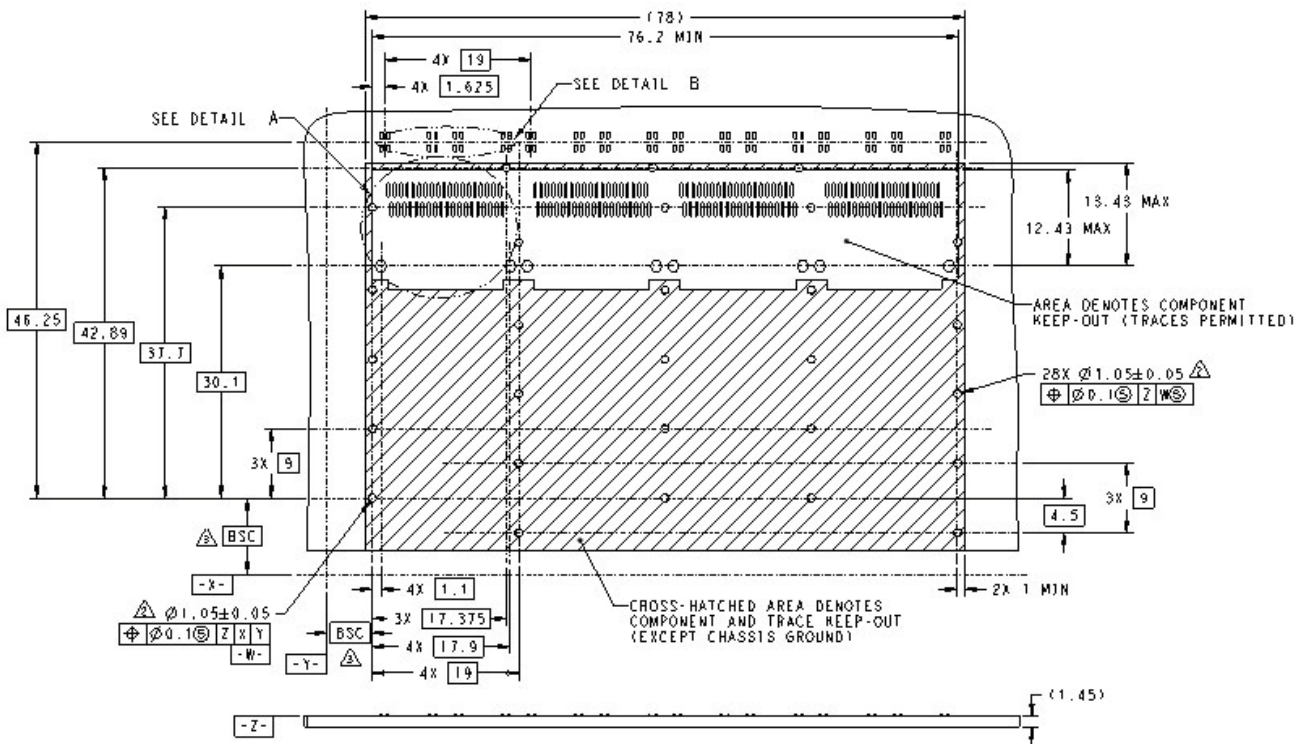
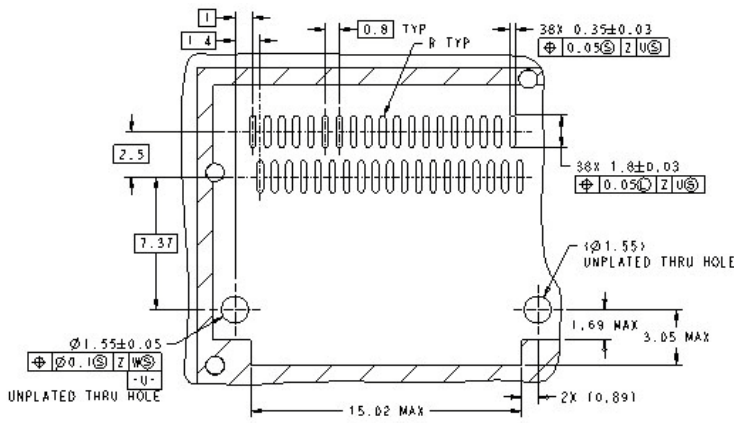


Figure 2 (Cont'd)

Detail A
Recommended Connector Layout



Detail B
Recommend LED Layout

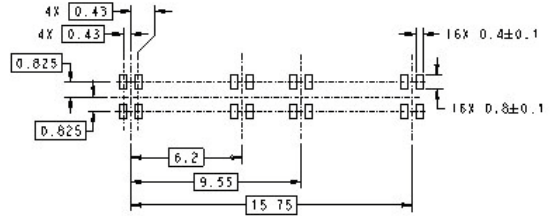
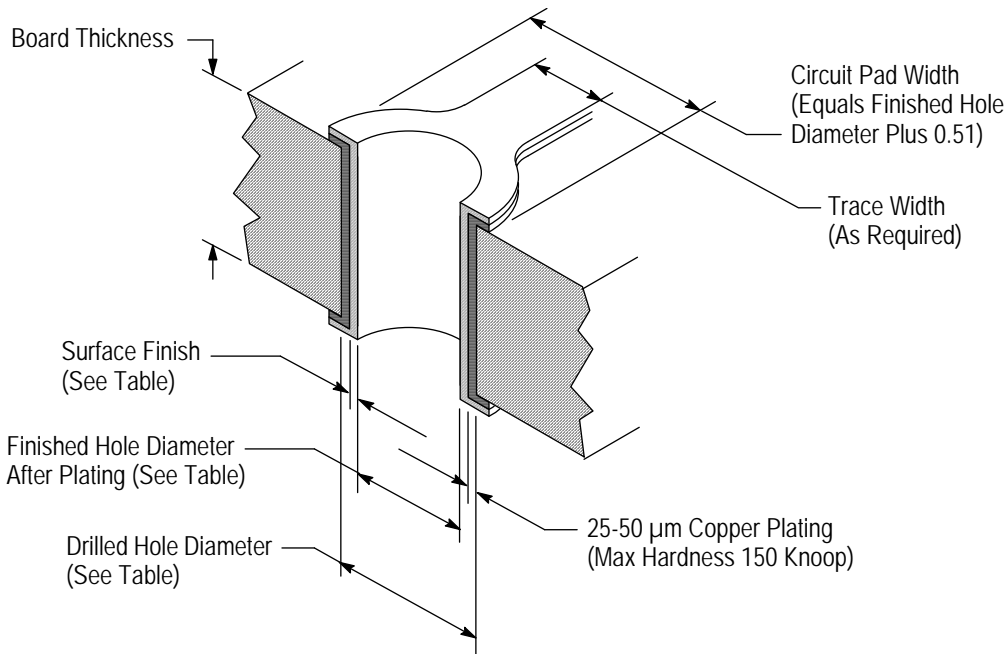


Figure 2 (End)

E. Hole Dimensions

The contact alignment post holes and cage assembly compliant pin holes must be drilled and plated through to specific dimensions to prevent stubbing during placement of the connector and cage assembly on the pc board. The drilled hole size, plating types, and plating thickness are dependent on the application requirements. The finished hole size must be as stated to provide unrestricted insertion. See Figure 3.



SURFACE FINISH	DRILLED HOLE DIAMETER	FINISHED HOLE DIAMETER	SURFACE FINISH THICKNESS
HASL SnPb	1.15 +0.02	1.05 Ref	0.004-0.010
Immersion Sn	1.15 +0.02	1.05 Ref	0.0005 Min.
OSP	1.15 +0.02	1.05 Ref	0.0002-0.0005
Immersion Au/Ni	1.15 +0.02	1.05 Ref	0.004-0.0076 (Ni) 0.0001-0.0005 (Au)

Figure 3

3.7. Bezel



It is strongly recommended that this bezel configuration NOT be used for PCI applications. The following requirements were intended to be used in the communications industry only.

A. Thickness

The bezel thickness range shall be 0.8 mm through 2.6 mm.

B. Cutout

The bezel must provide a cutout that allows proper mounting of the cage assembly. The cage assembly EMI gasket must be compressed by the bezel in order to provide an electrical ground between the cage assembly and bezel for EMI suppression. Care must be used to avoid interference between adjacent cage assemblies and other components. The minimum allowable distance between cage assemblies must be considered to ensure proper assembly. Dimensions for bezel cutout and minimum allowable distance between cutouts are shown in Figure 4.

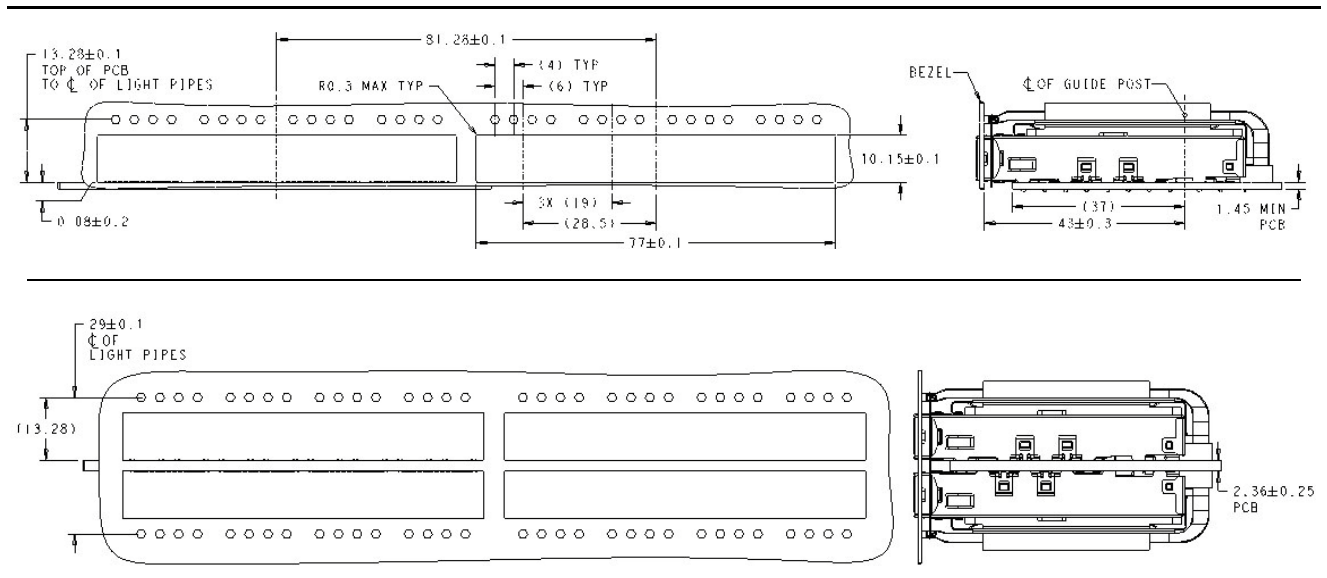
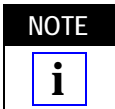


Figure 4

3.8. Cage Assembly Placement



The connector must be soldered to the pc board BEFORE seating the cage.

A. Registration

The compliant pin contacts must be aligned with matching holes in the pc board, then inserted into the pc board simultaneously to prevent twisting or bending of these parts.

B. Seating



A customer supplied pc board support fixture must be used to provide proper support for the host pc board, and to prevent damage to the host pc board and adjacent components. Wall supports must be properly installed to support the cage assembly. Refer to Section 5 for design requirements.

Using proper seating force and seating height is essential to interconnection performance. The force used to seat the cage assembly must be applied evenly to prevent deformation or other damage to compliant pin contacts. The force required to seat the cage assembly onto the pc board can be calculated by:

$$\text{Amount of Compliant Pin Contacts} \times 44.5 \text{ N [10 lbs]} \text{ (Force per Compliant Pin Contact)} = \text{Seating Force}$$



Over-driving the cage assembly will deform parts critical to the quality of the connection. Maximum force occurs prior to the cage assembly bottoming on the pc board.

When using tooling to seat the cage assembly, the shut height of the application tool must be specifically set for proper seating of the cage assembly. The shut height can be calculated by:

$$\text{Seating Height (Cage Assembly Seated) + Height of Seating Tool + Combined Thickness of PC Board and PCB Support Fixture = Shut Height (Ram Down)}$$



The shut height may need to be adjusted to maintain the 0.10 mm maximum gap dimension between the standoffs of the cage assembly and the pc board.

3.9. Checking Installed Cage Assembly

After installation, the cage assembly EMI gasket must be compressed by the bezel and the lenses of any light pipes used must be visible thru the bezel. A slight bow in the cage assembly is permitted.

3.10. Dust Cover

A dust cover must be installed into the port when the module is not mated with the cage assembly.

3.11. Light Pipe

A light pipe may be installed on various zQSFP+ cage assemblies. They can be used either with or without the appropriate heat sink, but must be installed after the heat sink and heat clip if these items are being used. Contact PRODUCT INFORMATION at the bottom of page 1 for combinations of heat sinks and light pipes.

The bezel must have an additional cut-out for each port on which a light pipe will be installed. See Figure 4 for placement of these cut-outs. The appropriate location of the LED's on the host pc board is provided in Figure 2, Detail B.

3.12. Removal and Repair

The optional light pipe can be removed by first lifting the front end of the light pipe out of the light pipe bracket on the front of the cage assembly. Then apply pressure to the outside of the arms of the light pipe, pressing them toward each other while gently pulling the light pipe back from the rear of the cage. As long as the light pipe is not cracked or warped, it can be re-used on any thru bezel cage assembly that has a light pipe bracket.



The cage assembly must be removed from the host pc board before removing the connector. Standard de-soldering methods must be used to remove the connector from the host pc board. The connector MUST NOT be re-used after removal. The connector and cage assembly are not repairable. Any defective or damaged products MUST NOT be re-used.

The clip (that secures the heat sink) must be removed using a tool (such as a small screwdriver or hobby knife) according to the following:

1. Insert the tip of the tool into either release aperture of the clip, and rotate the tool until the corresponding locking windows are released from the cage locking latches of the cage assembly. Repeat this step for the remaining release aperture. See Section 6.
2. Lift the clip and heat sink from the cage assembly.



The heat sink must be removed from the cage assembly before removing the cage assembly from the host pc board. A flat metal bar (or similar object) can be partially inserted into the front of the cage assembly (the object MUST NOT touch the connector; otherwise, damage to the contacts could occur). The cage assembly can then be removed by lifting it off the pc board. The cage assembly MUST NOT be re-used after removal.

4. QUALIFICATIONS

zQSFP+ connectors have not yet been sent for agency evaluation.

5. TOOLING

No tooling is required for manual placement of the cage assembly onto the pc board. For placement of a single zQSFP+ cage assembly onto the host pc board, flat rock tooling may be used.

CAUTION

Extreme caution must be used not to touch or damage the EMI springs during seating.



A pc board support fixture must be used to provide proper support for the host pc board, and to prevent damage to the host pc board and its adjacent components during seating of the cage assembly. It must have a flat surface with holes or a channel wide and deep enough to receive any protruding components during seating of the cage assembly on the host pc board. See Figure 5.

NOTE: The customer designed pc board support should be designed using the pc board layout from the specific customer print.

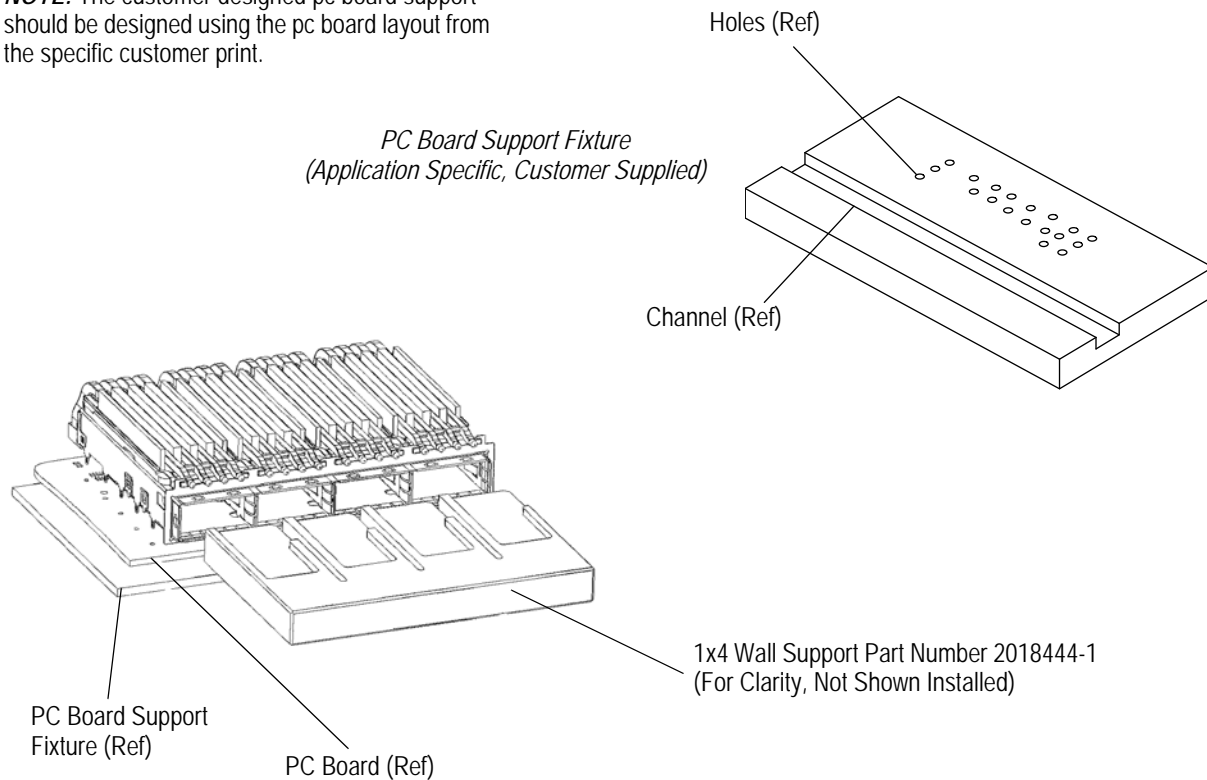


Figure 5

6. VISUAL AID

The illustration below shows a typical application of this product. This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

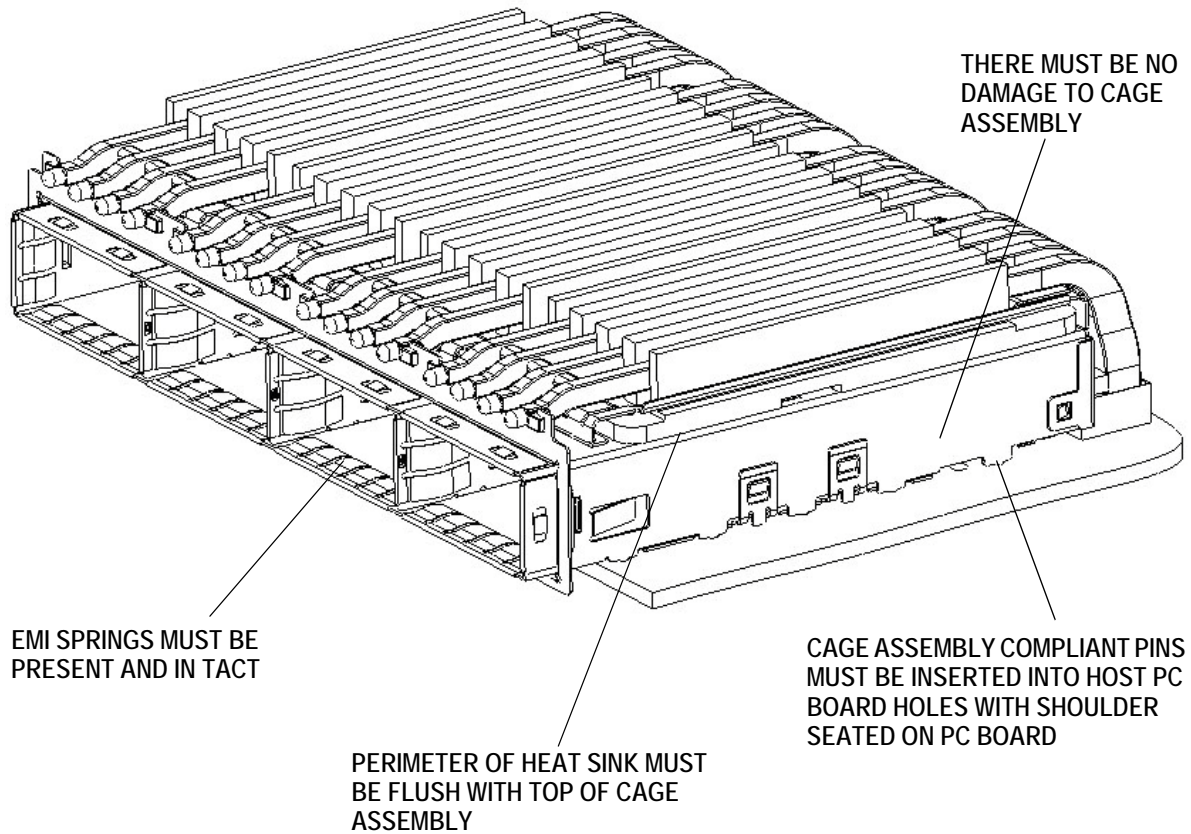


FIGURE 6. VISUAL AID